

Title (en)  
 DEVICE FOR FORMING A REDUCED CHAMBER SPACE AND METHOD FOR POSITIONING MULTILAYER BODIES

Title (de)  
 EINRICHTUNG ZUM AUSBILDEN EINES REDUZIERTEN KAMMERRAUMS, SOWIE VERFAHREN ZUM POSITIONIEREN VON MEHRSCICHTKÖRPERN

Title (fr)  
 DISPOSITIF POUR FORMER UN ESPACE DE CHAMBRE RÉDUIT ET PROCÉDÉ POUR POSITIONNER DES CORPS MULTICOUCHES

Publication  
**EP 2539926 B1 20230510 (DE)**

Application  
**EP 11708425 A 20110222**

Priority  

- EP 10154363 A 20100223
- EP 2011052597 W 20110222
- EP 11708425 A 20110222

Abstract (en)  
 [origin: EP2360720A1] The device (30a) has a part for forming side wall elements of a process box (20a), where the device retains objects i.e. multilayered bodies (40, 50), such that the objects lie opposite to each other and surfaces (44, 54) of the objects are turned away from each other. A processing element is arranged between the objects, and transverse connecting elements have supporting elements i.e. pointed supporting elements e.g. ball elements, such that the bodies are supported in the connecting elements by the supporting elements. Independent claims are also included for the following: (1) a system for processing objects comprising a gas supplying element and/or a gas discharging element for supplying and/or discharging process gas into and/or from a chamber area and/or a process chamber (2) a method for positioning objects.

IPC 8 full level  
**H01L 21/673** (2006.01); **C23C 16/458** (2006.01); **H01L 21/67** (2006.01); **H01L 31/18** (2006.01)

CPC (source: EP KR US)  
**B23Q 3/00** (2013.01 - US); **C23C 16/4582** (2013.01 - EP US); **H01L 21/67109** (2013.01 - EP US); **H01L 21/673** (2013.01 - KR); **H01L 21/67346** (2013.01 - EP US); **H01L 21/67353** (2013.01 - EP US); **H01L 21/67383** (2013.01 - EP US); **H01L 21/68** (2013.01 - KR); **H01L 31/18** (2013.01 - KR); **H01L 31/1876** (2013.01 - EP US); **Y02E 10/50** (2013.01 - US); **Y02E 10/541** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP US); **Y10T 29/49998** (2015.01 - EP US)

Citation (examination)  
 DE 19936081 A1 20010208 - SIEMENS AG [DE]

Designated contracting state (EPC)  
 AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2360720 A1 20110824**; CN 102763208 A 20121031; EA 201290686 A1 20130228; EP 2539926 A1 20130102; EP 2539926 B1 20230510; ES 2946533 T3 20230720; JP 2013520790 A 20130606; JP 2015156485 A 20150827; KR 101663918 B1 20161007; KR 20120123097 A 20121107; KR 20150067386 A 20150617; US 2013067723 A1 20130321; US 9352431 B2 20160531; WO 2011104231 A1 20110901; ZA 201206146 B 20130424

DOCDB simple family (application)  
**EP 10154363 A 20100223**; CN 201180010715 A 20110222; EA 201290686 A 20110222; EP 11708425 A 20110222; EP 2011052597 W 20110222; ES 11708425 T 20110222; JP 2012553347 A 20110222; JP 2015021094 A 20150205; KR 20127021936 A 20110222; KR 20157013829 A 20110222; US 201113580322 A 20110222; ZA 201206146 A 20120815